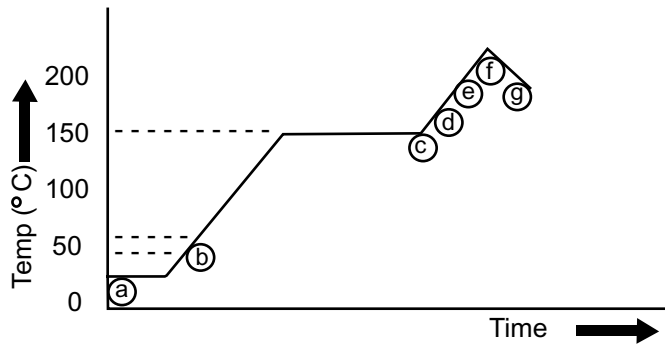
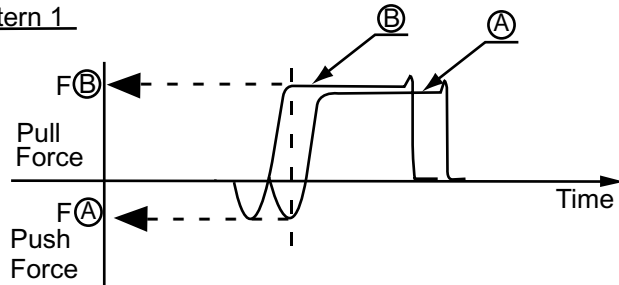


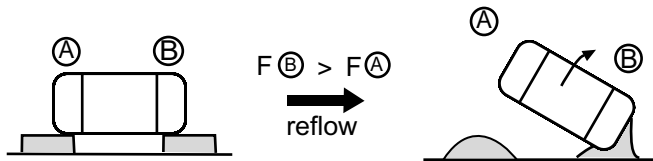
Reflow Profile



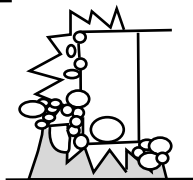
Pattern 1



Tombstoning can occur when the difference between F Ⓐ and F ⓑ is large.



Pattern 2



When heated, trapped air in solder paste vaporizes as foam, which will push the chip termination from bottom.

| Profile Region | Soldering Effect on Component | | |
|------------------|-------------------------------|-----------|-----------|
| (a) | | | |
| (b) | | | |
| (c) | | | |
| | Good | Pattern 1 | Pattern 2 |
| (d) 175-185°C | | | |
| (e) 185-195°C | | | |
| (f) 220-230°C | | | |
| (g) | | | |